Automotive Electronics Council

Component Technical Committee

Agenda

(subject to change)

2014 - Sixteenth Annual Automotive Electronics Reliability Workshop

April 22, 23, & 24

Novi, MI Sheraton Detroit Novi Hotel

Tuesday, April 22, 2014				
		7:30 am - 8:00 am	Continental Breakfast (provided)	
		8:00 am - 8:30 am	Workshop Introductions	
	1.1	8:30 am - 9:00 am	Jayson Young KEMET	Polymer Tantalum Capacitors for Automotive Applications
Session 1: Passive/Discrete Component Technology 8:30 am - 10:30 am	1.2	9:00 am - 9:30 am	Reiner Kuehl Vishay BC Components	Stability of Components During Biased Humidity Testing and Application
	1.3	9:30 am - 10:00 am	Peter Blais KEMET	SMD and Leaded Ceramic Capacitors For High Temperature Applications
	1.4	10:00 am - 10:30 am	Charles Pothier Vishay Intertechnology	New Tantalum Capacitor Technologies Ensure Reliability in the Next Generation of Automotive Electronics
		10:30 am - 11:00 am	BREAK: Coffee, drinks, snacks (p	provided)
Workshop Session - W.1		11:00 am - 12:00 pm	LED Qualification Review & Discussion Moderator: Ludger Kappius, Hella KGaA	
		12:00 pm - 1:30 pm	LUNCH (on own)	
Workshop Session - W.2		1:30 pm - 3:00 pm	Q200 Document Revision Status & Discussion Moderator: AEC Q200 Technical Committee	
		3:00 pm - 3:30 pm	BREAK: coffee, drinks, snacks (pr	rovided)
Workshop Session - W.3 3:30 pm - 5:00 pm Q101 Document Status & Discussion Moderator: AEC Q101 Technical Committee		vittee		
		5:00 PM	SESSION CLOSE	

Wednesday, April 23, 2014					
		7:30 am - 8:00 am	Continental Breakfast (provided)		
Session 2:	2.1	8:00 am - 8:30 am	Wolfgang Reinprecht AMS	Advanced Latch-up Testing of HV Automotive IC's	
Semiconductor Technology - Part 1	2.2	8:30am - 9:00am	Warren Chen <i>Macronix International</i>	NAND Flash Qualification Challenges for Automotive Applications	
8:00 am - 11:00 am	2.3	9:00 am - 9:30 am	Sebastiano Russo STMicroelectronics	Reliability of New Pb-Free Die Attach Materials for Power Devices	
9:30 am - 10:00 am BREAK: Coffee, drinks, snacks (provided)					
Session 2: (Continued)	2.4	10:00 am - 10:30 am	Shin Low Xilinx	High Performance Flip Chip Packaging for High Reliability Semiconductor Devices	
	2.5	10:30 am - 11:00 am	Eric Lei Global Foundries	Evaluation of 40LP SRAM HTOL 150degC for Automotive Grade 0 Application	
Workshop Session - W.4 11:00 am - 12:00 pm		Robustness Validation and Failure Rates - "Sample Sizes in Reliability Testing" Moderator: Werner Kanert, Infineon Technologies			
		12:00 pm - 1:30 pm	LUNCH (on own)		

Wednesday, April 23, 2014 (continued)					
Session 3: Semiconductor Technology - Part 2 1:30 pm - 5:00 pm	3.1	1:30 pm - 2:00 pm	Ludger Kappius <i>Hella KGaA</i>	ZVEI Delta Qualification Matrix	
	3.2	2:00 pm - 2:30 pm	Joop Verwijst NXP Semiconductors	Parameter Shift Analysis	
	3.3	2:30 pm - 3:00 pm	Anil Gandhi Qualicent Analytics	Advanced Analytics for Automotive Zero Defect	
	3.4	3:00 pm - 3:30 pm	Tim Haifley <i>Altera</i>	A Complete Lifetime Distribution	
3:30 pm - 4:00 pm BREAK: Coffee, drinks, snacks (provided)					
Session 3: (Continued)	3.5	4:00 pm - 4:30 pm	Weiyen Kuo TSMC	Cpk Challenges in Nanometer Semiconductor Technology	
	3.6	4:30 pm - 5:00 pm	Megan Smitter GE Aviation	Collaborative Approach For Practical Modeling of Microcircuit Failures in High-Reliability Applications	
	3.7	5:00 pm - 5:30 pm	Tim Haifley <i>Altera</i>	Combining Data From Similar Tests: A Bayesian Approach	
		5:30 pm - 7:30 pm	DINNER (on own)		
Workshop Session - W.5 7:30 pm - 9:30 p		7:30 pm - 9:30 pm	Q100 Document Review & Discussion Moderator: AEC Q100 Technical Committee		

Thursday, April 24, 2014					
COFFEE (provided)	7:30 am - 8:00 am	Continental Breakfast provided			
Workshop Session - W.6	8:00 am - 9:00 am	Known Good Die / Multi-Chip Module Moderator: Tom Lawler, Lattice Semiconductor			
Workshop Session - W.7	9:00 am - 10:00 am	MEMS Moderator: Earl Fischer, Autoliv			
	10:00 am - 10:30 am	BREAK: Coffee, drinks, snacks (provided)			
Workshop Session - W.8	10:30 am - 11:00 am	Touch Systems Moderator: Joe Lucia, John Deere Electonic Solutions	ì		
Workshop Session - W.9	11:00 am - 11:30 am	System-Level ESD Moderator: TBD			
Workshop Session - W.10	11:30 am - 12:00 pm	PC Board Qualification Moderator: James McLeish, DfR Solutions			
WRAP-UP	12:00 pm - 12:30 pm	AEC Technical Committee	Closing Statements & Workshop Adjourned		